

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Mizuki NAGAI et al.

Serial No. 10/664,078

Filed September 17, 2003

COPPER-PLATING LIQUID, PLATING  
METHOD AND PLATING APPARATUS



: Confirmation No. 5067

: Docket No. 2003\_1338

: Group Art Unit 1753

: Examiner Edna Wong

**Mail Stop: Amendment**

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**RESPONSE**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Official Action dated January 11, 2005, the period for response having been extended for three months by the attached petition, please amend the present application as follows:

07/12/2005 HALI11 00000101 10664078

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1050.00 OP